

## Low Voltage 1:18 Clock Distribution Chip

### Features

- LVPECL or LVCMOS Clock Input
- 2.5V LVCMOS Outputs for Pentium II Microprocessor Support\*
- 150pS Maximum Output-to-Output Skew
- Maximum Output Frequency of 250MHz
- 32 Lead LQFP & TQFP Packaging
- Dual or Single Supply Device
- Dual  $V_{CC}$  Supply Voltage, 3.3V Core and 2.5V Output
- Single 3.3V  $V_{CC}$  Supply Voltage for 3.3V Outputs
- Single 2.5V  $V_{CC}$  Supply Voltage for 2.5V I/O
- Pin and Function compatible to MPC940L, MPC9109, CY29940 and CY29940-1

### Functional Description

The ASM2I9940L is a 1:18 low Voltage Clock distribution chip with 2.5V or 3.3V LVCMOS output capabilities. The device features the capability to select either a differential LVPECL or LVCMOS compatible input. The 18 outputs are 2.5V or 3.3V LVCMOS compatible and feature the drive strength to drive  $50\Omega$  series or parallel terminated transmission lines. With output-to-output skews of 150pS, the ASM2I9940L is ideal as a clock distribution chip for the most demanding of Synchronous systems. The 2.5V outputs also make the device ideal for supplying clocks for a high performance microprocessor based design.

With low output impedance ( $\approx 20\Omega$ ), in both the HIGH and LOW logic states, the output buffers of the ASM2I9940L are ideal for driving series terminated transmission lines. With  $20\Omega$  output impedance the ASM2I9940L has the capability of driving two series terminated lines from each output. This gives the device an effective fanout of 1:36.

The differential LVPECL inputs of the ASM2I9940L allow the device to interface directly with a LVPECL fanout buffer to build very wide clock fanout trees or to couple to a high frequency clock source. The LVCMOS input provides a more standard interface for applications requiring only a single clock distribution chip at relatively low frequencies. In addition, the two clock sources can be used to provide for a test clock interface as well as the primary system clock. A logic HIGH on the LVCMOS\_CLK\_Sel pin will select the LVCMOS level clock input. All inputs of the ASM2I9940L have internal pullup/pulldown resistor, so they can be left open if unused.

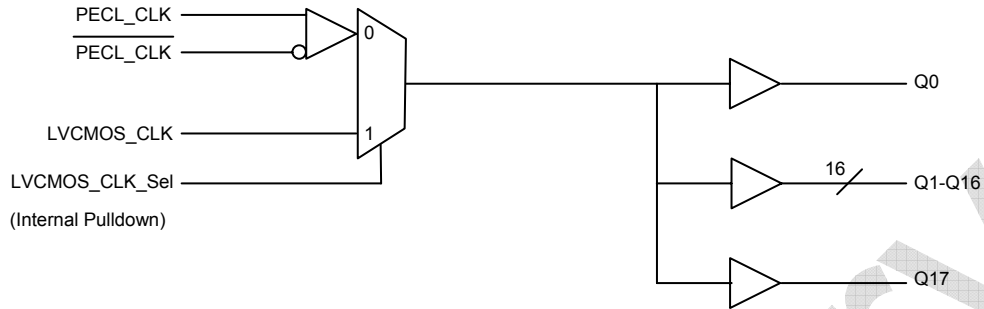
The ASM2I9940L is a single or dual supply device. The device power supply offers a high degree of flexibility. The device can operate with a 3.3V core and 3.3V output, a 3.3V core and 2.5V outputs as well as a 2.5V core and 2.5V outputs. The 32-lead LQFP and TQFP Packages were chosen to optimize performance, board space and cost of the device. The 32-lead LQFP and TQFP Packages have a  $7 \times 7 \text{mm}^2$  body size with conservative 0.8mm pin spacing.

\* Pentium II is a trademark of Intel Corporation

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Block Diagram



Pin Diagram

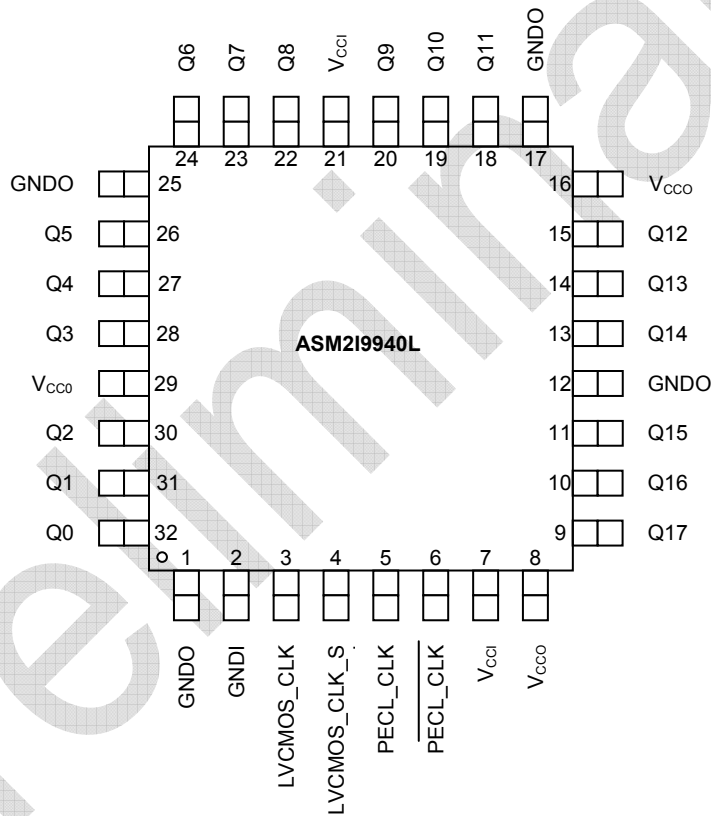


Table 1. Function Table

| LVC MOS_CLK_Sel | Input       |
|-----------------|-------------|
| 0               | PECL_CLK    |
| 1               | LVC MOS_CLK |

Table 2. Power Supply Voltages

| Supply Pin       | Voltage Level     |
|------------------|-------------------|
| V <sub>CC1</sub> | 2.5V or 3.3V ± 5% |
| V <sub>CC0</sub> | 2.5V or 3.3V ± 5% |

**Table 3. Pin Configuration**

| Pin #  | Pin Name          | I/O    | Type    | Function   |
|--|-------------------|--------|---------|--|
| 5  | PECL_CLK          | Input  | LVPECL  | LVPECL Clock Inputs                                    |
| 6  | PECL_CLK          |        |         |  |
| 3  | LVC MOS_CLK       | Input  | LVC MOS | LVC MOS Clock Input                                    |
| 4  | LVC MOS_CLK_Sel   | Input  | LVC MOS | Selects either LVPECL or LVC MOS input as Clock Source |
| 32,31,30,28,27,26,24,23,22,20,19,18,15,14,13,11,10,9 | Q0-Q17            | Output | LVC MOS | Clock Outputs  |
| 2  | GNDI              |        | Supply  | Core Negative Power Supply                             |
| 1,12,17,25   | GND O             |        | Supply  | Output Negative Power Supply                           |
| 7,21   | V <sub>CC I</sub> |        | Supply  | Core Positive Power Supply                             |
| 8, 16,29   | V <sub>CC O</sub> |        | Supply  | Output Positive Power Supply                           |

**Table 4. Absolute Maximum Ratings<sup>1</sup>**

| Symbol            | Parameter  | Min  | Max                   | Unit |
|-------------------|--|------|-----------------------|------|
| V <sub>CC</sub>   | Supply Voltage   | -0.3 | 3.6                   | V    |
| V <sub>I</sub>    | Input Voltage  | -0.3 | V <sub>CC</sub> + 0.3 | V    |
| I <sub>IN</sub>   | Input Current  |      | ±20                   | mA   |
| T <sub>Stor</sub> | Storage Temperature Range                                | -40  | 125                   | °C   |
| T <sub>s</sub>    | Max. Soldering Temperature (10 sec)                      |      | 260                   | °C   |
| T <sub>DV</sub>   | Static Discharge Voltage<br>(As per JEDEC STD22- A114-B) |      | 2                     | KV   |

Note:1. These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

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**Table 5. DC Characteristics** ( $T_A = -40^\circ$  to  $+85^\circ\text{C}$ ,  $V_{CC1} = 3.3\text{V} \pm 5\%$ ,  $V_{CC0} = 3.3\text{V} \pm 5\%$ )

| Symbol    | Characteristic                   |          | Min          | Typ | Max          | Unit          | Condition               |
|-----------|----------------------------------|----------|--------------|-----|--------------|---------------|-------------------------|
| $V_{IH}$  | Input HIGH Voltage               | CMOS_CLK | 2.0          |     | $V_{CC1}$    | V             |                         |
| $V_{IL}$  | Input LOW Voltage                | CMOS_CLK |              |     | 0.8          | V             |                         |
| $V_{PP}$  | Peak-to-Peak Input Voltage       | PECL_CLK | 500          |     | 1000         | mV            |                         |
| $V_{CMR}$ | Common Mode Range                | PECL_CLK | $V_{CC}-1.4$ |     | $V_{CC}-0.6$ | V             |                         |
| $V_{OH}$  | Output HIGH Voltage              |          | 2.4          |     |              | V             | $I_{OH} = -20\text{mA}$ |
| $V_{OL}$  | Output LOW Voltage               |          |              |     | 0.5          | V             | $I_{OH} = 20\text{mA}$  |
| $I_{IN}$  | Input Current                    |          |              |     | $\pm 200$    | $\mu\text{A}$ |                         |
| $C_{IN}$  | Input Capacitance                |          |              | 4.0 |              | pF            |                         |
| $C_{pd}$  | Power Dissipation Capacitance    |          |              | 10  |              | pF            | per output              |
| $Z_{OUT}$ | Output Impedance                 |          | 18           | 23  | 28           | $\Omega$      |                         |
| $I_{CC}$  | Maximum Quiescent Supply Current |          |              | 0.5 | 1.0          | mA            |                         |

**Table 6. AC Characteristics** ( $T_A = -40^\circ$  to  $+85^\circ\text{C}$ ,  $V_{CC1} = 3.3\text{V} \pm 5\%$ ,  $V_{CC0} = 3.3\text{V} \pm 5\%$ )

| Symbol       | Characteristic          |  | Min        | Typ        | Max        | Unit   | Condition                        |
|--------------|-------------------------|--|------------|------------|------------|--------|----------------------------------|
| $F_{max}$    | Maximum Input Frequency |  |            |            | 250        | MHz    |                                  |
| $t_{PLH}$    | Propagation Delay       | PECL_CLK $\leq$ 150MHz<br>CMOS_CLK $\leq$ 150MHz | 2.0<br>1.7 | 2.7<br>2.5 | 3.4<br>3.0 | nS     | Note <sup>1</sup>                |
| $t_{PLH}$    | Propagation Delay       | PECL_CLK $>$ 150MHz<br>CMOS_CLK $>$ 150MHz       | 2.0<br>1.8 | 2.9<br>2.5 | 3.7<br>3.2 | nS     |                                  |
| $t_{sk(o)}$  | Output-to-output Skew   | PECL_CLK<br>CMOS_CLK                             |            |            | 150<br>150 | pS     | Note <sup>1</sup>                |
| $t_{sk(pp)}$ | Part-to-Part Skew       | PECL_CLK $<$ 150MHz<br>CMOS_CLK $<$ 150MHz       |            |            | 1.5<br>1.3 | nS     | Notes <sup>1,2</sup>             |
| $t_{sk(pp)}$ | Part-to-Part Skew       | PECL_CLK $>$ 150MHz<br>CMOS_CLK $>$ 150MHz       |            |            | 1.8<br>1.5 | nS     | Notes <sup>1,2</sup>             |
| $t_{sk(pp)}$ | Part-to-Part Skew       | PECL_CLK CMOS_CLK                                |            |            | 850<br>750 | pS     | Notes <sup>1,3</sup>             |
| DC           | Output Duty Cycle       | $f_{CLK} <$ 134 MHz<br>$f_{CLK} \leq$ 250 MHz    | 45<br>40   | 50<br>50   | 55<br>60   | %<br>% | Input DC = 50%<br>Input DC = 50% |
| $t_r, t_f$   | Output Rise/Fall Time   |  | 0.3        |            | 1.1        | nS     | 0.5 – 2.4 V                      |

Note: 1. Tested using standard input levels, Production tested @ 150MHz.

2. Across temperature and voltage ranges, includes output skew.

3. For a specific temperature and voltage, includes output skew.

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**Table 7. DC Characteristics** ( $T_A = -40^\circ$  to  $+85^\circ\text{C}$ ,  $V_{CC1} = 3.3\text{V} \pm 5\%$ ,  $V_{CC0} = 2.5\text{V} \pm 5\%$ )

| Symbol    | Characteristic                   |          | Min          | Typ | Max          | Unit          | Condition               |
|-----------|----------------------------------|----------|--------------|-----|--------------|---------------|-------------------------|
| $V_{IH}$  | Input HIGH Voltage               | CMOS_CLK | 2.0          |     | $V_{CC1}$    | V             |                         |
| $V_{IL}$  | Input LOW Voltage                | CMOS_CLK |              |     | 0.8          | V             |                         |
| $V_{PP}$  | Peak-to-Peak Input Voltage       | PECL_CLK | 500          |     | 1000         | mV            |                         |
| $V_{CMR}$ | Common Mode Range                | PECL_CLK | $V_{CC}-1.4$ |     | $V_{CC}-0.6$ | V             |                         |
| $V_{OH}$  | Output HIGH Voltage              |          | 1.8          |     |              | V             | $I_{OH} = -20\text{mA}$ |
| $V_{OL}$  | Output LOW Voltage               |          |              |     | 0.5          | V             | $I_{OH} = 20\text{mA}$  |
| $I_{IN}$  | Input Current                    |          |              |     | $\pm 200$    | $\mu\text{A}$ |                         |
| $C_{IN}$  | Input Capacitance                |          |              | 4.0 |              | pF            |                         |
| $C_{pd}$  | Power Dissipation Capacitance    |          |              | 10  |              | pF            | per output              |
| $Z_{OUT}$ | Output Impedance                 |          |              | 23  |              | $\Omega$      |                         |
| $I_{CC}$  | Maximum Quiescent Supply Current |          |              | 0.5 | 1.0          | mA            |                         |

**Table 8. AC Characteristics** ( $T_A = -40^\circ$  to  $+85^\circ\text{C}$ ,  $V_{CC1} = 3.3\text{V} \pm 5\%$ ,  $V_{CC0} = 2.5\text{V} \pm 5\%$ )

| Symbol       | Characteristic          |  | Min        | Typ        | Max        | Unit   | Condition                        |
|--------------|-------------------------|--|------------|------------|------------|--------|----------------------------------|
| $F_{max}$    | Maximum Input Frequency |  |            |            | 250        | MHz    |                                  |
| $t_{PLH}$    | Propagation Delay       | PECL_CLK $\leq$ 150MHz<br>CMOS_CLK $\leq$ 150MHz | 2.0<br>1.7 | 2.8<br>2.5 | 3.5<br>3.0 | nS     | Note <sup>1</sup>                |
| $t_{PLH}$    | Propagation Delay       | PECL_CLK $>$ 150MHz<br>CMOS_CLK $>$ 150MHz       | 2.0<br>1.8 | 2.9<br>2.5 | 3.8<br>3.3 | nS     |                                  |
| $t_{sk(o)}$  | Output-to-output Skew   | PECL_CLK<br>CMOS_CLK                             |            |            | 150<br>150 | pS     | Note <sup>1</sup>                |
| $t_{sk(pp)}$ | Part-to-Part Skew       | PECL_CLK $<$ 150MHz<br>CMOS_CLK $<$ 150MHz       |            |            | 1.5<br>1.3 | nS     | Notes <sup>1,2</sup>             |
| $t_{sk(pp)}$ | Part-to-Part Skew       | PECL_CLK $>$ 150MHz<br>CMOS_CLK $>$ 150MHz       |            |            | 1.8<br>1.5 | nS     | Notes <sup>1,2</sup>             |
| $t_{sk(pp)}$ | Part-to-Part Skew       | PECL_CLK CMOS_CLK                                |            |            | 850<br>750 | pS     | Notes <sup>1,3</sup>             |
| DC           | Output Duty Cycle       | $f_{CLK} <$ 134 MHz<br>$f_{CLK} \leq$ 250 MHz    | 45<br>40   | 50<br>50   | 55<br>60   | %<br>% | Input DC = 50%<br>Input DC = 50% |
| $t_r, t_f$   | Output Rise/Fall Time   |  | 0.3        |            | 1.2        | nS     | 0.5 - 1.8 V                      |

Note: 1. Tested using standard input levels, Production tested @ 150MHz.  
 2. Across temperature and voltage ranges, includes output skew.  
 3. For a specific temperature and voltage, includes output skew.

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**Table 9. DC Characteristics** ( $T_A = -40^\circ$  to  $+85^\circ\text{C}$ ,  $V_{CCI} = 2.5\text{V} \pm 5\%$ ,  $V_{CCO} = 2.5\text{V} \pm 5\%$ )

| Symbol    | Characteristic                   |          | Min          | Typ | Max          | Unit          | Condition               |
|-----------|----------------------------------|----------|--------------|-----|--------------|---------------|-------------------------|
| $V_{IH}$  | Input HIGH Voltage               | CMOS_CLK | 2.0          |     | $V_{CCI}$    | V             |                         |
| $V_{IL}$  | Input LOW Voltage                | CMOS_CLK |              |     | 0.8          | V             |                         |
| $V_{PP}$  | Peak-to-Peak Input Voltage       | PECL_CLK | 500          |     | 1000         | mV            |                         |
| $V_{CMR}$ | Common Mode Range                | PECL_CLK | $V_{CC}-1.0$ |     | $V_{CC}-0.6$ | V             |                         |
| $V_{OH}$  | Output HIGH Voltage              |          | 1.8          |     |              | V             | $I_{OH} = -20\text{mA}$ |
| $V_{OL}$  | Output LOW Voltage               |          |              |     | 0.5          | V             | $I_{OH} = 20\text{mA}$  |
| $I_{IN}$  | Input Current                    |          |              |     | $\pm 200$    | $\mu\text{A}$ |                         |
| $C_{IN}$  | Input Capacitance                |          |              | 4.0 |              | pF            |                         |
| $C_{pd}$  | Power Dissipation Capacitance    |          |              | 10  |              | pF            | per output              |
| $Z_{OUT}$ | Output Impedance                 |          | 18           | 23  | 28           | $\Omega$      |                         |
| $I_{CC}$  | Maximum Quiescent Supply Current |          |              | 0.5 | 1.0          | mA            |                         |

**Table 10. AC Characteristics** ( $T_A = -40^\circ$  to  $+85^\circ\text{C}$ ,  $V_{CCI} = 2.5\text{V} \pm 5\%$ ,  $V_{CCO} = 2.5\text{V} \pm 5\%$ )

| Symbol       | Characteristic                           |  | Min        | Typ        | Max        | Unit   | Condition                        |
|--------------|--|--|------------|------------|------------|--------|----------------------------------|
| $F_{max}$    | Maximum Input Frequency                  |  |            |            | 200        | MHz    |                                  |
| $t_{PLH}$    | Propagation Delay                        | PECL_CLK $\leq$ 150MHz<br>CMOS_CLK $\leq$ 150MHz | 2.6<br>2.3 | 4.0<br>3.1 | 5.2<br>4.0 | nS     | Note <sup>1</sup>                |
| $t_{PLH}$    | Propagation Delay                        | PECL_CLK $>$ 150MHz<br>CMOS_CLK $>$ 150MHz       | 2.8<br>2.3 | 3.8<br>3.1 | 5.0<br>4.0 | nS     |                                  |
| $t_{sk(o)}$  | Output-to-output Skew<br>Within one bank | PECL_CLK<br>CMOS_CLK                             |            |            | 200<br>200 | pS     | Note <sup>1</sup>                |
| $t_{sk(pp)}$ | Part-to-Part Skew                        | PECL_CLK $<$ 150MHz<br>CMOS_CLK $<$ 150MHz       |            |            | 2.6<br>1.7 | nS     | Notes <sup>1,2</sup>             |
| $t_{sk(pp)}$ | Part-to-Part Skew                        | PECL_CLK $>$ 150MHz<br>CMOS_CLK $>$ 150MHz       |            |            | 2.2<br>1.7 | nS     | Notes <sup>1,2</sup>             |
| $t_{sk(pp)}$ | Part-to-Part Skew                        | PECL_CLK<br>CMOS_CLK                             |            |            | 1.2<br>1.0 | nS     | Notes <sup>1,3</sup>             |
| DC           | Output Duty Cycle                        | $f_{CLK} <$ 134 MHz<br>$f_{CLK} \leq$ 250 MHz    | 45<br>40   | 50<br>50   | 55<br>60   | %<br>% | Input DC = 50%<br>Input DC = 50% |
| $t_r, t_f$   | Output Rise/Fall Time                    |  | 0.3        |            | 1.2        | nS     | 0.5 - 1.8 V                      |

Note: 1. Tested using standard input levels, Production tested @ 150MHz.

2. Across temperature and voltage ranges, includes output skew.

3. For a specific temperature and voltage, includes output skew.

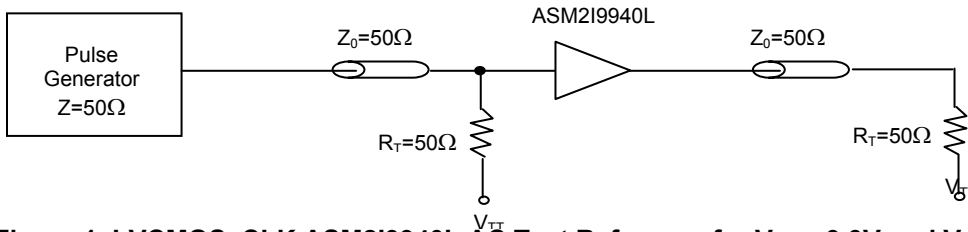


Figure 1. LVC MOS\_CLK ASM2I9940L AC Test Reference for  $V_{CC} = 3.3V$  and  $V_{CC} = 2.5V$

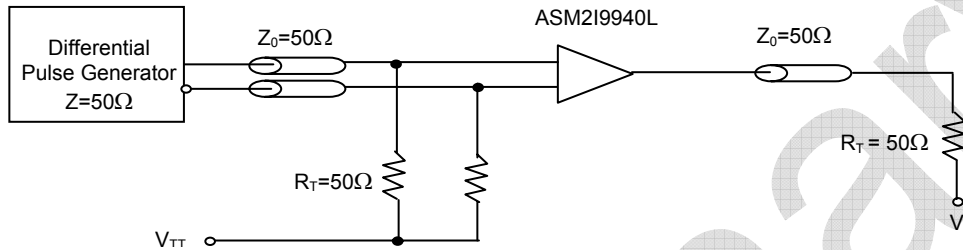


Figure 2. PECL\_CLK ASM2I9940L AC Test Reference for  $V_{CC} = 3.3V$  and  $V_{CC} = 2.5V$

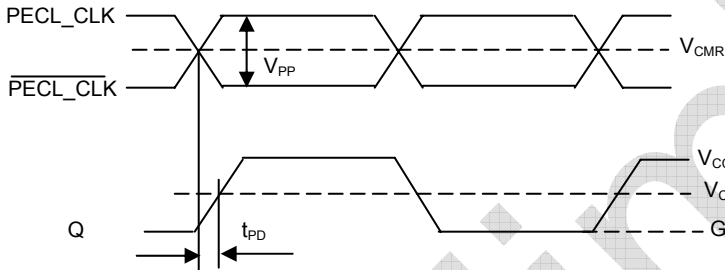


Figure 3. Propagation Delay ( $t_{PD}$ ) Test Reference

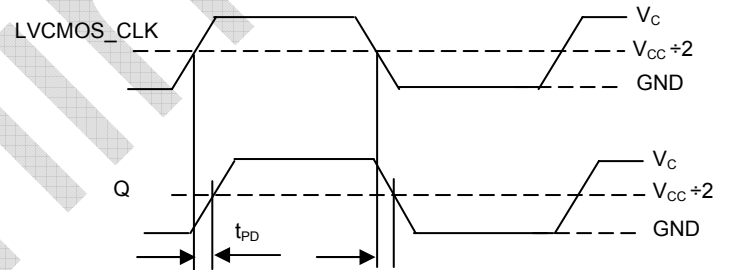
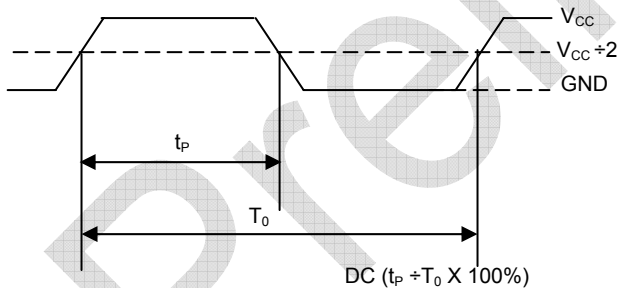
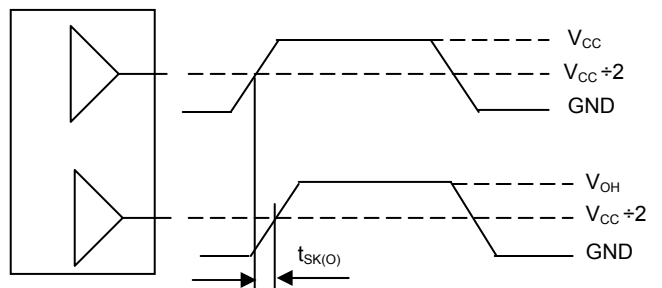


Figure 4. LVC MOS Propagation Delay ( $t_{PD}$ ) Test Reference



The time from the PLL controlled edge to the non-controlled edge, divided by the time between PLL controlled edges, expressed as a percentage.

Figure 5. Output Duty Cycle (DC)



The pin-to-pin skew is defined as the worst case difference in propagation delay between any similar delay path within a single device

Figure 6. Output-to-Output Skew  $t_{SK(O)}$

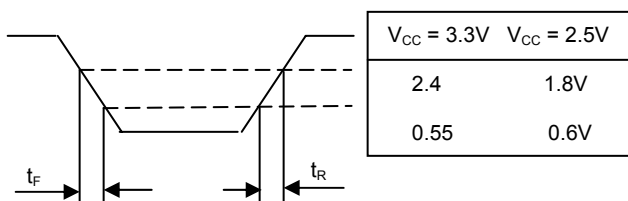


Figure 7. Output Transition Time Test Reference

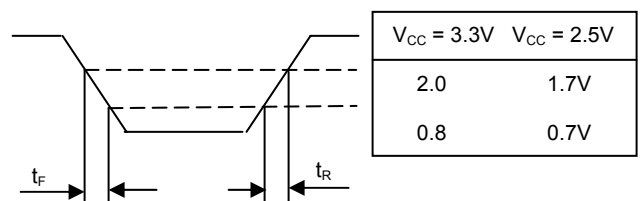


Figure 8. Input Transition Time Test Reference



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**Power Consumption of the ASM2I9940L and Thermal Management**

The ASM2I9940L AC specification is guaranteed for the entire operating frequency range up to 250MHz. The ASM2I9940L power consumption and the associated long-term reliability may decrease the maximum frequency limit, depending on operating conditions such as clock frequency, supply voltage, output loading, ambient temperature, vertical convection and thermal conductivity of package and board. This section describes the impact of these parameters on the junction temperature and gives a guideline to estimate the ASM2I9940L die junction temperature and the associated device reliability.

**Table 11. Die junction temperature and MTBF**

| Junction temperature (°C) | MTBF (Years) |
|---------------------------|--------------|
| 100                       | 20.4         |
| 110                       | 9.1          |
| 120                       | 4.2          |
| 130                       | 2.0          |

Increased power consumption will increase the die junction temperature and impact the device reliability (MTBF). According to the system-defined tolerable MTBF, the die junction temperature of the ASM2I9940L needs to be controlled and the thermal impedance of the board/package should be optimized. The power dissipated in the ASM2I9940L is represented in equation 1.

$$P_{TOT} = \left[ I_{CCQ} + V_{CC} \cdot f_{CLOCK} \cdot \left( N \cdot C_{PD} + \sum_M C_L \right) \right] \cdot V_{CC} \tag{Equation 1}$$

$$P_{TOT} = V_{CC} \cdot \left[ I_{CCQ} + V_{CC} \cdot f_{CLOCK} \cdot \left( N \cdot C_{PD} + \sum_M C_L \right) \right] + \sum_P \left[ DC_Q \cdot I_{OH} (V_{CC} - V_{OH}) + (1 - DC_Q) \cdot I_{OL} \cdot V_{OL} \right] \tag{Equation 2}$$

$$T_J = T_A + P_{TOT} \cdot R_{thja} \tag{Equation 3}$$

$$f_{CLOCKMAX} = \frac{1}{C_{PD} \cdot N \cdot V_{CC}^2} \cdot \left[ \frac{T_{JMAX} - T_A}{R_{thja}} - (I_{CCQ} \cdot V_{CC}) \right] \tag{Equation 4}$$

Where  $I_{CCQ}$  is the static current consumption of the ASM2I9940L,  $C_{PD}$  is the power dissipation capacitance per output,  $(M)\sum C_L$  represents the external capacitive output load,  $N$  is the number of active outputs ( $N$  is always 12 in case of the ASM2I9940L). The ASM2I9940L supports driving transmission lines to maintain high signal integrity and tight timing parameters. Any transmission line will hide the lumped capacitive load at the end of the board trace, therefore,  $\sum C_L$  is zero for controlled transmission line systems and can be eliminated from equation 1. Using parallel termination output termination results in equation 2 for power dissipation.

In equation 2,  $P$  stands for the number of outputs with a parallel or thevenin termination,  $V_{OL}$ ,  $I_{OL}$ ,  $V_{OH}$  and  $I_{OH}$  are a function of the output termination technique and  $DC_Q$  is the clock signal duty cycle. If transmission lines are used  $\sum C_L$  is zero in equation 2 and can be eliminated. In general, the use of controlled transmission line techniques eliminates the impact of the lumped capacitive loads at the end lines and greatly reduces the power dissipation of the device. Equation 3 describes the die junction temperature  $T_J$  as a function of the power consumption.

Where  $R_{thja}$  is the thermal impedance of the package (junction to ambient) and  $T_A$  is the ambient temperature. According to Table 11, the junction temperature can be used to estimate the long-term device reliability. Further, combining equation 1 and equation 2 results in a maximum operating frequency for the ASM2I9940L in a series terminated transmission line system, equation 4.



$T_{j,MAX}$  should be selected according to the MTBF system requirements and Table 11.  $R_{thja}$  can be derived from Table 12. The  $R_{thja}$  represent data based on 1S2P boards, using 2S2P boards will result in a lower thermal impedance than indicated below.

**Table 12. Thermal package impedance of the 32LQFP**

| Convection, LFPM | $R_{thja}$ (1P2S board), °C/W | $R_{thja}$ (2P2S board), °C/W |
|------------------|-------------------------------|-------------------------------|
| Still air        | 86                            | 61                            |
| 100 lfpm         | 76                            | 56                            |
| 200 lfpm         | 71                            | 54                            |
| 300 lfpm         | 68                            | 53                            |
| 400 lfpm         | 66                            | 52                            |
| 500 lfpm         | 60                            | 49                            |

If the calculated maximum frequency is below 250MHz, it becomes the upper clock speed limit for the given application conditions. The following eight derating charts describe the safe frequency operation range for the ASM2I9940L. The charts were calculated for a maximum tolerable die junction temperature of 110°C (120°C), corresponding to an estimated MTBF of 9.1 years (4 years), a supply voltage of 3.3V and series terminated transmission line or capacitive loading. Depending on a given set of these operating conditions and the available device convection a decision on the maximum operating frequency can be made.

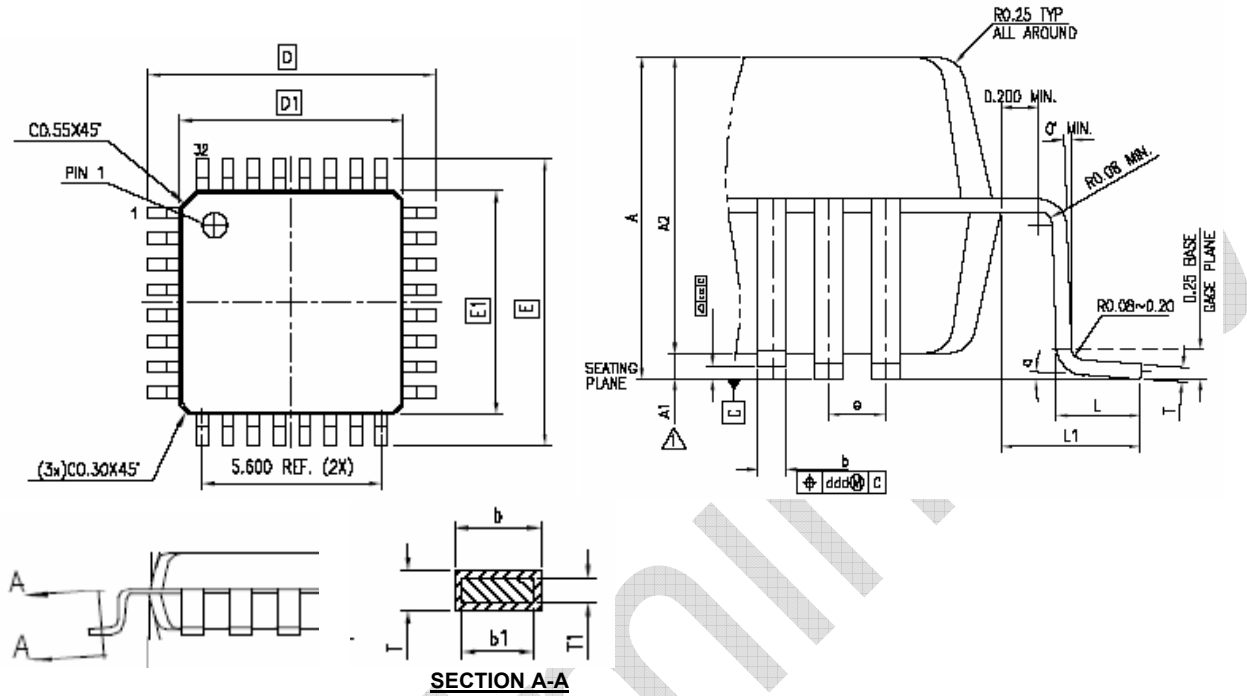
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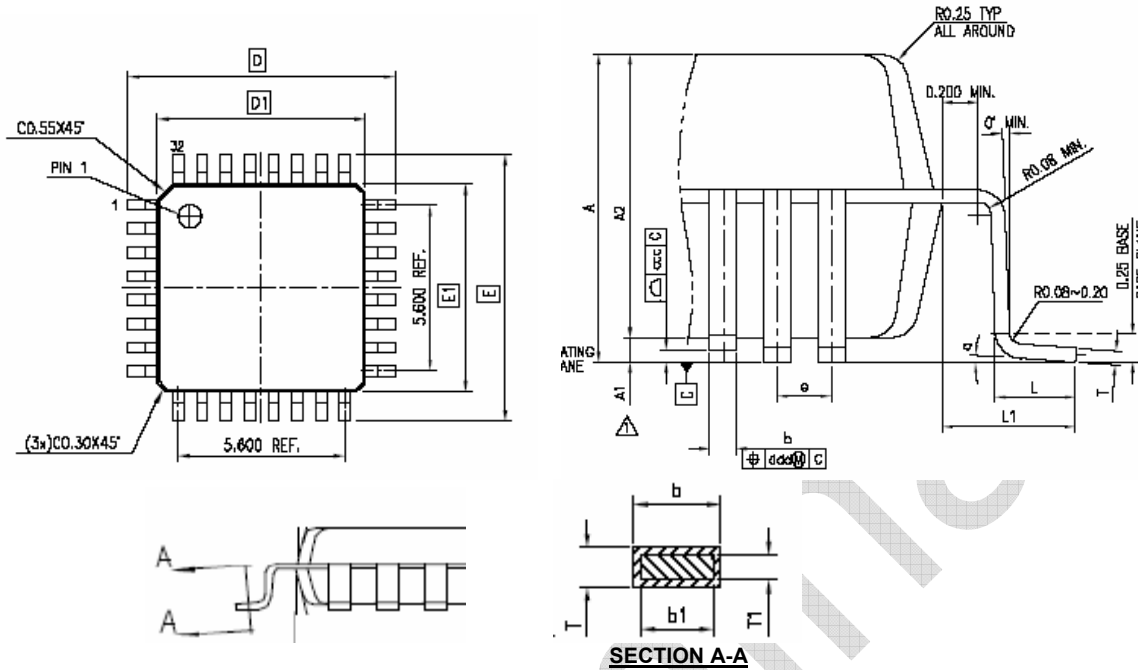
Package Information

32-lead TQFP



| Symbol | Dimensions  |        |             |       |
|--------|-------------|--------|-------------|-------|
|        | Inches      |        | Millimeters |       |
|        | Min         | Max    | Min         | Max   |
| A      | ....        | 0.0472 | ...         | 1.2   |
| A1     | 0.0020      | 0.0059 | 0.05        | 0.15  |
| A2     | 0.0374      | 0.0413 | 0.95        | 1.05  |
| D      | 0.3465      | 0.3622 | 8.8         | 9.2   |
| D1     | 0.2717      | 0.2795 | 6.9         | 7.1   |
| E      | 0.3465      | 0.3622 | 8.8         | 9.2   |
| E1     | 0.2717      | 0.2795 | 6.9         | 7.1   |
| L      | 0.0177      | 0.0295 | 0.45        | 0.75  |
| L1     | 0.03937 REF |        | 1.00 REF    |       |
| T      | 0.0035      | 0.0079 | 0.09        | 0.2   |
| T1     | 0.0038      | 0.0062 | 0.097       | 0.157 |
| b      | 0.0118      | 0.0177 | 0.30        | 0.45  |
| b1     | 0.0118      | 0.0157 | 0.30        | 0.40  |
| R0     | 0.0031      | 0.0079 | 0.08        | 0.2   |
| a      | 0°          | 7°     | 0°          | 7°    |
| e      | 0.031 BASE  |        | 0.8 BASE    |       |

32-lead LQFP



| Symbol | Dimensions  |        |             |       |
|--------|-------------|--------|-------------|-------|
|        | Inches      |        | Millimeters |       |
|        | Min         | Max    | Min         | Max   |
| A      | ....        | 0.0630 | ...         | 1.6   |
| A1     | 0.0020      | 0.0059 | 0.05        | 0.15  |
| A2     | 0.0531      | 0.0571 | 1.35        | 1.45  |
| D      | 0.3465      | 0.3622 | 8.8         | 9.2   |
| D1     | 0.2717      | 0.2795 | 6.9         | 7.1   |
| E      | 0.3465      | 0.3622 | 8.8         | 9.2   |
| E1     | 0.2717      | 0.2795 | 6.9         | 7.1   |
| L      | 0.0177      | 0.0295 | 0.45        | 0.75  |
| L1     | 0.03937 REF |        | 1.00 REF    |       |
| T      | 0.0035      | 0.0079 | 0.09        | 0.2   |
| T1     | 0.0038      | 0.0062 | 0.097       | 0.157 |
| b      | 0.0118      | 0.0177 | 0.30        | 0.45  |
| b1     | 0.0118      | 0.0157 | 0.30        | 0.40  |
| R0     | 0.0031      | 0.0079 | 0.08        | 0.20  |
| e      | 0.031 BASE  |        | 0.8 BASE    |       |
| a      | 0°          | 7°     | 0°          | 7°    |

Ordering Information

| Part Number       | Marking      | Package Type                      | Operating Range |
|-------------------|--------------|-----------------------------------|-----------------|
| ASM2P9940LG-32-LT | ASM2P9940LGL | 32-pin LQFP, Tray, Green          | Commercial      |
| ASM2P9940LG-32-LR | ASM2P9940LGL | 32-pin LQFP, Tape and Reel, Green | Commercial      |
| ASM2P9940LG-32-ET | ASM2P9940LGE | 32-pin TQFP, Tray, Green          | Commercial      |
| ASM2P9940LG-32-ER | ASM2P9940LGE | 32-pin TQFP, Tape and Reel, Green | Commercial      |
| ASM2I9940LG-32-LT | ASM2I9940LGL | 32-pin LQFP, Tray, Green          | Industrial      |
| ASM2I9940LG-32-LR | ASM2I9940LGL | 32-pin LQFP, Tape and Reel, Green | Industrial      |
| ASM2I9940LG-32-ET | ASM2I9940LGE | 32-pin TQFP, Tray, Green          | Industrial      |
| ASM2I9940LG-32-ER | ASM2I9940LGE | 32-pin TQFP, Tape and Reel, Green | Industrial      |

Device Ordering Information

A S M 2 I 9 9 4 0 L G - 3 2 - L R

R = Tape & Reel, T = Tube or Tray

|           |           |
|-----------|-----------|
| O = SOT   | U = MSOP  |
| S = SOIC  | E = TQFP  |
| T = TSSOP | L = LQFP  |
| A = SSOP  | U = MSOP  |
| V = TVSOP | P = PDIP  |
| B = BGA   | D = QSOP  |
| Q = QFN   | X = SC-70 |

DEVICE PIN COUNT

G = GREEN PACKAGE, LEAD FREE, and RoHS

PART NUMBER

|                                |                               |                                    |
|--------------------------------|-------------------------------|------------------------------------|
| X = Automotive (-40C to +125C) | I = Industrial (-40C to +85C) | P or n/c = Commercial (0C to +70C) |
|--------------------------------|-------------------------------|------------------------------------|

|                           |                      |
|---------------------------|----------------------|
| 1 = Reserved              | 6 = Power Management |
| 2 = Non PLL based         | 7 = Power Management |
| 3 = EMI Reduction         | 8 = Power Management |
| 4 = DDR support products  | 9 = Hi Performance   |
| 5 = STD Zero Delav Buffer | 0 = Reserved         |

PulseCore Semiconductor Mixed Signal Product

Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.



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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to PulseCore Semiconductor, dated 11-11-2003

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